



**SLOVENSKI STANDARD**  
**oSIST prEN IEC 62007-2:2024**  
**01-februar-2024**

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**Polprevodniške optoelektronske naprave za uporabo v sistemih z optičnimi vlakni**  
**- 2. del: Merilne metode**

Semiconductor optoelectronic devices for fibre optic system applications - Part 2:  
Measuring methods

Optoelektronische Halbleiterbauelemente für Anwendungen in Lichtwellenleitersystemen  
- Teil 2: Messverfahren

Dispositifs optoélectroniques à semiconducteurs pour application dans les systèmes  
fibroniques - Partie 2: Méthodes de mesure

**Ta slovenski standard je istoveten z: prEN IEC 62007-2:2023**

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31.260	Optoelektronika, laserska oprema	Optoelectronics. Laser equipment
33.180.01	Sistemi z optičnimi vlakni na splošno	Fibre optic systems in general

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**en**





# 86C/1895/CDV

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OF INTEREST TO THE FOLLOWING COMMITTEES:	PROPOSED HORIZONTAL STANDARD: <input type="checkbox"/> Other TC/SCs are requested to indicate their interest, if any, in this CDV to the secretary.
FUNCTIONS CONCERNED: <input type="checkbox"/> EMC <input type="checkbox"/> ENVIRONMENT <input checked="" type="checkbox"/> QUALITY ASSURANCE <input type="checkbox"/> SAFETY	
<input checked="" type="checkbox"/> SUBMITTED FOR CENELEC PARALLEL VOTING <b>Attention IEC-CENELEC parallel voting</b> The attention of IEC National Committees, members of CENELEC, is drawn to the fact that this Committee Draft for Vote (CDV) is submitted for parallel voting. The CENELEC members are invited to vote through the CENELEC online voting system.	<input type="checkbox"/> NOT SUBMITTED FOR CENELEC PARALLEL VOTING

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TITLE:  
**Semiconductor optoelectronic devices for fibre optic system applications - Part 2: Measuring methods**

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NOTE FROM TC/SC OFFICERS:

## CONTENTS

1		
2		
3	FOREWORD .....	4
4	INTRODUCTION .....	6
5	1 Scope .....	7
6	2 Normative references .....	7
7	3 Terms, definitions, and abbreviated terms .....	7
8	3.1 Terms and definitions .....	7
9	3.2 Abbreviated terms .....	7
10	4 Measuring methods for photoemitters .....	8
11	4.1 Outline of the measuring methods .....	8
12	4.2 Radiant power and forward current of LEDs and LDs with or without optical fibre pigtails .....	8
13	4.3 Small signal cut-off frequency $f_c$ of LEDs and LDs with or without optical fibre pigtails .....	9
14	4.4 Threshold current of LDs with or without optical fibre pigtails .....	11
15	4.5 Relative intensity noise of LEDs and LDs with or without optical fibre pigtails .....	12
16	4.6 $S_{11}$ parameter of LEDs, LDs, and LD modules with or without optical fibre pigtails .....	13
17	4.7 Tracking error for LD modules with optical fibre pigtails, with or without cooler .....	15
18	4.8 Spectral linewidth of LDs with or without optical fibre pigtails .....	17
19	4.9 Modulation current at 1 dB efficacy compression of LEDs .....	19
20	4.10 Differential efficiency of an LD module or an LD with or without pigtail .....	21
21	4.11 Differential (forward) resistance $r_d$ of an LD with or without pigtail .....	22
22	5 Measuring methods for receivers .....	23
23	5.1 Outline of the measuring methods .....	23
24	5.2 Noise of a PIN photodiode .....	24
25	5.3 Excess noise factor of an APD with or without optical fibre pigtails .....	25
26	5.4 Small-signal cut-off frequency of a photodiode with or without optical fibre pigtails .....	27
27	5.5 Multiplication factor of an APD with or without an optical fibre pigtail .....	28
28	5.6 Responsivity of a PIN-TIA module .....	30
29	5.7 Frequency response flatness ( $\Delta S/S$ ) of a PIN-TIA module .....	32
30	5.8 Output noise power (spectral) density $P_{no,\lambda}$ of a PIN-TIA module .....	33
31	5.9 Low frequency output noise power (spectral) density ( $P_{no,\lambda,LF}$ ) and corner frequency ( $f_{cor}$ ) of a PIN-TIA module .....	35
32	5.10 Minimum detectable power of PIN-TIA module .....	37
33	Bibliography .....	39
34		
35	Figure 1 – Equipment setup for measuring radiant power and forward current of LEDs or LDs .....	9
36	Figure 2 – Circuit diagram for measuring the small-signal cut-off frequency of LEDs or LDs 10	
37	Figure 3 – Circuit diagram for measuring threshold current of LDs .....	11
38	Figure 4 – Graph to determine threshold current of LDs .....	12

47	Figure 5 – Circuit diagram for measuring RIN of LEDs or LDs .....	12
48	Figure 6 – Circuit diagram for measuring the $S_{11}$ parameter of LEDs, LDs, or LD	
49	modules .....	14
50	Figure 7– Circuit diagrams for LDs with cathode or anode connected to package .....	16
51	Figure 8 – Output radiant power versus time .....	17
52	Figure 9 – Output radiant power versus case temperature .....	17
53	Figure 10 – Equipment setup for measuring the spectral linewidth of LDs .....	18
54	Figure 11 – Circuit diagram for measuring 1-dB efficacy compression of LEDs .....	19
55	Figure 12 – Plot of $20 \times \log(V_2)$ versus $20 \times \log(I_1)$ .....	20
56	Figure 13 – Circuit diagram for measuring differential efficiency of LDs .....	21
57	Figure 14 – Current waveform for differential efficiency measurement .....	21
58	Figure 15 – Circuit diagram for measuring differential resistance of LDs .....	22
59	Figure 16 – Current waveform for differential resistance .....	23
60	Figure 17 – Circuit diagram for measuring noise of a PIN photoreceiver .....	24
61	Figure 18 – Circuit diagram for measuring noise with synchronous detection .....	25
62	Figure 19 – Circuit diagram for measuring excess noise of an APD .....	26
63	Figure 20 – Circuit diagram for measuring small-signal cut-off wavelength of a	
64	photodiode .....	28
65	Figure 21 – Circuit diagram for measuring multiplication factor of an APD .....	29
66	Figure 22 – Graph showing measurement of $I_{R1}$ and $I_{R2}$ .....	30
67	Figure 23 – Circuit diagram for measuring responsivity of a PIN-TIA module .....	31
68	Figure 24 – Circuit diagram for measuring frequency response flatness of a PIN-TIA	
69	module .....	32
70	Figure 25 – Circuit diagram for measuring output noise power (spectral) density of a	
71	PIN-TIA module under matched output conditions .....	34
72	Figure 26 – Circuit diagram for measuring output noise power (spectral) density of a	
73	non-irradiated PIN-TIA module in the low frequency region .....	35
74	Figure 27 – Graph of $V_m$ versus frequency .....	37
75	Figure 28 – Circuit diagram for measuring minimum detectable power of a PIN-TIA	
76	module .....	38

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR OPTOELECTRONIC DEVICES  
FOR FIBRE OPTIC SYSTEM APPLICATIONS –****Part 2: Measuring methods**

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IEC 62007-2 has been prepared by subcommittee 86C: Fibre optic systems and active devices, of IEC technical committee 86: Fibre optics. It is an International Standard.

This third edition cancels and replaces the second edition published in 2009. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) Correction of an error in Formula (1) for relative intensity noise;
- b) Correction of errors in the title of Figure 11 and the text of 4.9 (replaced “LD” with “LED”);
- c) Clarification of how to calculate the 1 dB compression in 4.9;

135 d) Correction of an error in Figure 21 (added missing label “SA”);

136 e) Clarification of the measurement setup (Figure 28) in 5.10.

137 The text of this International Standard is based on the following documents:

Draft	Report on voting
86C/XX/FDIS	86C/XX/RVD

138  
139 Full information on the voting for its approval can be found in the report on voting indicated in  
140 the above table.

141 The language used for the development of this International Standard is English.

142 This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in  
143 accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available  
144 at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are  
145 described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

146 A list of all parts of the IEC 62007 series can be found, under the general title *Semiconductor*  
147 *optoelectronic devices for fibre optic system applications*, on the IEC website

148 The committee has decided that the contents of this document will remain unchanged until the  
149 stability date indicated on the IEC website under [webstore.iec.ch](http://webstore.iec.ch) in the data related to the  
150 specific document. At this date, the document will be

- 151 • reconfirmed,
- 152 • withdrawn,
- 153 • replaced by a revised edition, or
- 154 • amended.

155

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157

## INTRODUCTION

158 Semiconductor optical signal transmitters and receivers play important roles in optical  
159 information networks. This standard covers the measurement procedures for their optical and  
160 electrical properties that are intended for digital communication systems. These properties are  
161 essential to specify their performance.

162

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# SEMICONDUCTOR OPTOELECTRONIC DEVICES FOR FIBRE OPTIC SYSTEM APPLICATIONS –

## Part 2: Measuring methods

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165  
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167

### 1 Scope

169 This part of IEC 62007 specifies measuring methods for characterizing semiconductor  
170 optoelectronic devices that are used in the field of fibre optic digital communication systems  
171 and subsystems.

### 2 Normative references

173 There are no normative references in this document.

### 3 Terms, definitions, and abbreviated terms

#### 3.1 Terms and definitions

176 For the purposes of this document, the following terms, definitions and abbreviations apply.

177 ISO and IEC maintain terminology databases for use in standardization at the following  
178 addresses:

- 179 • IEC Electropedia: available at <https://www.electropedia.org/>
- 180 • ISO Online browsing platform: available at <https://www.iso.org/obp>

##### 3.1.1

##### **PIN photodiode**

183 photodiode with a large intrinsic region sandwiched between p- and n-doped semiconducting  
184 regions used for the detection of optical radiation [62007-2:2024](https://standards.iteh.ai/catalog/standards/sist/caa53815-51f3-4947-941f-df0199a097cd/osist-pren-iec-62007-2-2024)

185 [SOURCE: IEV 731-06-29]

##### 3.1.2

##### **avalanche photodiode**

188 photodiode operating with a bias voltage such that the primary photocurrent undergoes  
189 amplification by cumulative multiplication of charge carriers

190 [SOURCE: IEV 731-06-30]

##### 3.1.3

##### **pigtail**

193 short optical fibre or optical fibre cable that is attached to a device being measured

#### 3.2 Abbreviated terms

195	AC	alternating current
196	APD	avalanche photodiode
197	BER	bit-error ratio
198	DC	direct current
199	LED	light emitting diode
200	LD	laser diode

201	PD	photodetector
202	RF	radio frequency
203	RIN	relative intensity noise
204	RMS	root mean square
205	TIA	transimpedance amplifier

## 206 **4 Measuring methods for photoemitters**

### 207 **4.1 Outline of the measuring methods**

208 Light emitting diodes (LEDs) and laser diodes (LDs) have important opto-electronic properties,  
209 which need to be specified when they are used in optical communication systems. The  
210 measurement methods for characterizing these opto-electronic properties are described in  
211 subclauses 4.2 to 4.11, where each subclause covers the following topics.

- 212 a) Purpose;
- 213 b) One of the following items
  - 214 • Measurement equipment;
  - 215 • Equipment setup;
  - 216 • Circuit diagram;
  - 217 • Circuit design and current waveform for measurement.
- 218 c) Equipment / circuit description and requirements;
- 219 d) Precautions to be observed;
- 220 e) Measurement procedures;
- 221 f) Specified conditions.

222 If a device is equipped with an optical fibre pigtail, all optical fibres and cables defined in the  
223 IEC 60793 and IEC 60794 series are applicable. If a pigtail is to be terminated with an optical  
224 connector, all optical connectors defined in the IEC 61754 and IEC 61755 series are applicable.

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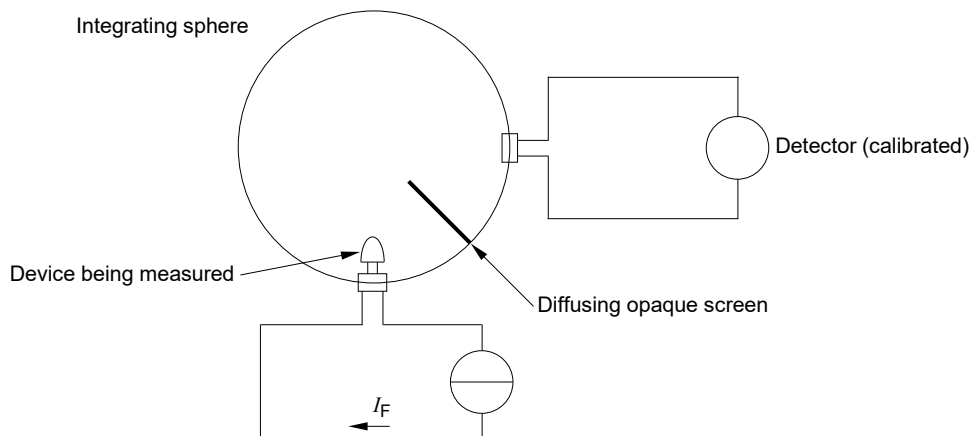
### 225 **4.2 Radiant power and forward current of LEDs and LDs with or without optical fibre** 226 **pigtails**

#### 227 *a) Purpose*

228 To measure the radiant power  $\Phi_e$  and the forward current  $I_F$  of LEDs and LDs, with or  
229 without optical fibre pigtails, under specified conditions.

#### 230 *b) Measurement equipment*

231 Figure 1 shows the equipment setup for measuring the radiant power and forward current  
232 of LEDs and LDs.



IEC 2305/08

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234

235

**Figure 1 – Equipment setup for measuring radiant power and forward current of LEDs or LDs**

236 **c) Equipment description and requirements**

237 The radiation emitted by the device is subjected to multiple reflections from the walls of the  
 238 integrating sphere; this leads to a uniform irradiance of the surface proportional to the  
 239 emitted flux. A detector located in the walls of the sphere measures this irradiance. An  
 240 opaque screen shields the detector from the direct radiation of the device being measured.

241 **d) Precautions to be observed**

242 The device being measured, the screen, and the apertures shall be small compared to the  
 243 sphere surface.

244 The inner surface of the sphere and screen shall have a diffusing coating with a high uniform  
 245 reflection coefficient (0,8 minimum).

246 The sphere and detector assembly shall be calibrated.

247 Variations in peak-emission wavelength and in radiation flux due to power dissipation shall  
 248 be taken into account.

249 When the radiation emitted by the device being measured is pulsed, the detector shall time-  
 250 average the measured radiation.

251 **e) Measurement procedures**

252 The emitting device is positioned at the entrance of the integrating sphere, so that no direct  
 253 radiation will reach the detector.

254 For measurements of radiant power, the specified forward current  $I_F$  is applied to the device,  
 255 and the radiant power is measured by the photodetector.

256 For measurements of forward current, the current applied to the device is increased until  
 257 the specified radiant power  $\Phi_e$  is achieved. The value of this current is recorded.

258 **f) Specified conditions**

- 259 – Ambient or case temperature.
- 260 – Radiant power (when measuring forward current).
- 261 – Forward current (when measuring radiant power).

262 **4.3 Small signal cut-off frequency  $f_c$  of LEDs and LDs with or without optical fibre pigtailed**

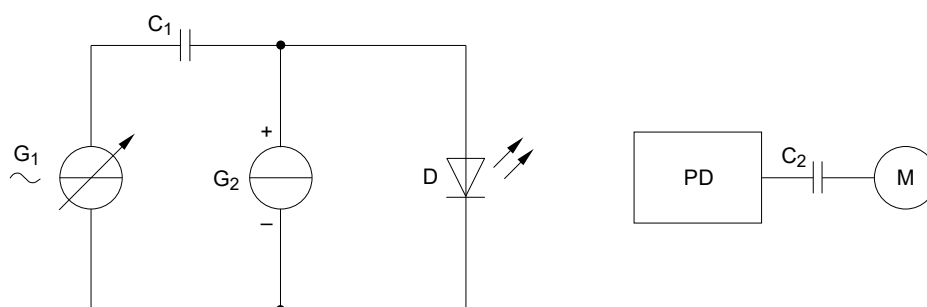
264 **a) Purpose**

265 To measure the small-signal cut-off frequency  $f_c$  of LEDs and LDs with or without optical  
 266 fibre pigtailed, under specified conditions.

267 **b) Circuit diagram**

268 Figure 2 shows a circuit diagram for measuring the small-signal cut-off frequency of  
269 LEDs and LDs.

270



IEC 2306/08

271

272 **Key**

273	D	device being measured
274	$G_1$	AC generator with adjustable frequency
275	$G_2$	DC generator
276	PD	photodetector
277	M	measuring instrument for AC radiant power
278	$C_1, C_2$	coupling capacitors

279

**Figure 2 – Circuit diagram for measuring the small-signal cut-off frequency of LEDs or LDs**

280

281 *c) Equipment description and requirements*

282 No requirements for this item.

283 *d) Precautions to be observed*

284 The radiant power reflected back into the laser diode shall be minimized to avoid modulation  
285 distortions, which could affect the accuracy of the measurement. The photodetector must  
286 have a frequency response greater than  $f_c$ .

287 *e) Measurement procedure*

288 For LEDs, the specified direct forward current or the direct forward current required to obtain  
289 the specified radiant power is applied to the device being measured.

290 For laser diodes, the forward current is adjusted to a value which is equal to the continuous  
291 forward current above threshold or which generates a specified radiant power.

292 The forward current is modulated using generator  $G_1$  at a low frequency  $f_1$  (less than  $f_c/100$ )  
293 and the AC radiant power is measured by instrument M (see Figure 2).

294 Keeping the modulation level constant, the modulation frequency is increased until the  
295 output radiant power measured by M is reduced to 50 % of the value obtained at  $f_1$ .

296 This frequency is the small-signal cut-off frequency  $f_c$ .

297 *f) Specified conditions*

298 For light-emitting diodes (LED):

- 299 – ambient or case temperature;
- 300 – DC forward current or radiant power.

301 For the laser diodes (LD):

- 302 – ambient, case, or submount temperature;
- 303 – radiant power or difference between applied DC forward current and threshold current of  
304 LD.